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# Enhancing Energy Efficiency of Sram through Optimization of Sram Array Structures

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**Abstract:** Reliability is a major concern in the microprocessor industry. In terms of power consumption, SRAM plays a key role in improving processing performance. Improving SRAM efficiency requires changes to the array structure. A general method in which the SRAM array has more rows than columns. The above techniques are proposed to improve efficiency by 10% for 8kbit and 40% for 64kbit at the same SRAM byte density and supply voltage. Implement suggested deep submicron technology for better reliability. Many proposed designs focus on low power consumption, often with reduced response times. As the technology scales, the power consumption of on-chain system devices with gate leakage, subthreshold current, and tunneling increases significantly. Small SRAM capabilities are important. This task demonstrates the potential of using larger SRAM array structures to achieve better SRAM energy efficiency, especially when the number of rows is less than the number of low-power columns. Compared to traditional 8T SRAM, the proposed 10T cell uses less power, has a different temperature and better performance.

**Keywords:** Low Scale, Gate Leakage Current, Sub Threshold Current.

## 1. INTRODUCTION

Most modern CMOS devices are used in low-power applications such as battery-powered computers, communication equipment, and aerospace [1]. Designers of these CMOS systems need to quickly and accurately predict the power consumption of their designs. The most common method is low energy consumption. The supply voltage is reduced below or near critical voltage [2]. In this area of operation, SRAM design is considered more difficult due to the additional design constraints on general-purpose digital logic, and other circuit technologies and successful hardware measurements have been published. The cell stability of separate SRAM cells is commonly used [3]. Some margin write problems can be used for the positive or negative boost voltage channel length modulation to improve the write access transistor and to drive the power supply voltage to 10T [4]-[6].

In their study, the optimum SRAM frame structure to minimise power consumption has more rows than columns and is not square, whereas it was found to be at least square in the optimal array structure for minimising access time for memories [7-10]. The static energy at very low energy voltages is similar to the dynamic energy required to test SRAM arrays with optimal structure [11].

This summary analyses SRAM energy efficiency improvement structures in ultra-low power systems. Section II describes the structures of common arrays. Section III describes the effects on subarrays and SRAM energy modelling considered for dual Vth schemes, including SRAM and 10-transistor (10T). Section IV analyses the effect of changes in the SRAM array structure on power consumption by deriving the optimum SRAM Array structure. Finally, Chapter V summarises this task and concludes it.

### Normal Array Structure

SRAM cells should be designed for non-destructive reading and writing. These requirements for the transistor size regulation of the SRAM cell. SRAM cells are powered, designed to provide the ability to read, write and store (or store information) in a non-destructive manner. We are discussing about the design and analysis of six (6T), (8T) and two different SRAM cells (10T). We have to compare them with power. The battery design should generally maintain the equilibrium between battery area, robustness, speed, losses and output. Reducing power consumption is one of the most important design goals.

### SRAM Array

Larger SRAM arrays can be built from smaller arrays. The external interface of the table is the same as a SRAM on the right [21-23]. Values are provided in the RAM structure at each address location to see the remaining data stored in each drawing (to the right of the decimal number, to the right of the address, to the right of the colour box). They are binary information). All 8x4 SRAM items have the same 4-bit data at the same 3-bit address point [7]. As shown in Figure 1.

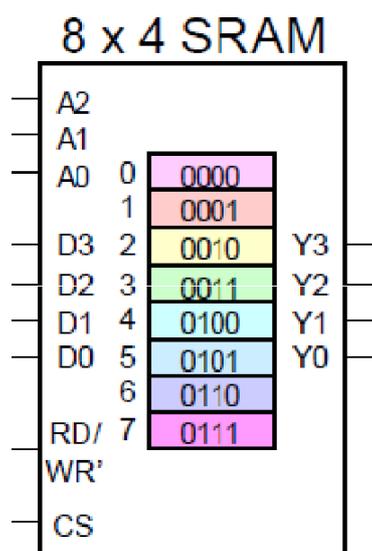


Figure 1: 8:4 SRAM

### Building Wider SRAMS

More SRAM can be used to build larger devices. Data input/output is divided into SRAM components. The address, chip select and RD/WR signals are the same for all devices [24-28]. All devices contain a subset of word bit locations from the entire memory. Multiple SRAMs can be used to create multi-row position devices. In Figure 2, the RD / WR signal can appear on the input data line and the lower order address bits will be the same on all chips.

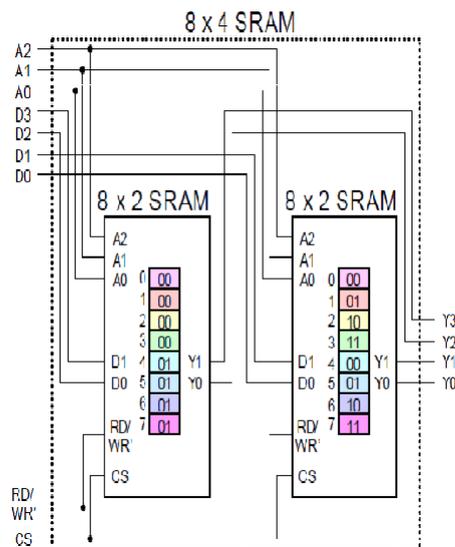


Figure 2: Wider SRAM Cell

### SRAM Array with 6T Cell

In Figure 3, four transistors are shown in the mainstream SRAM CMOS 6T. The four transistors are CMOS inverters connected between the transistors and two NMOS transistors (Q5 and Q6) to provide read/write access to the cell. SRAM 6T cells are the most widely used SRAM cells for low power consumption and low voltage.

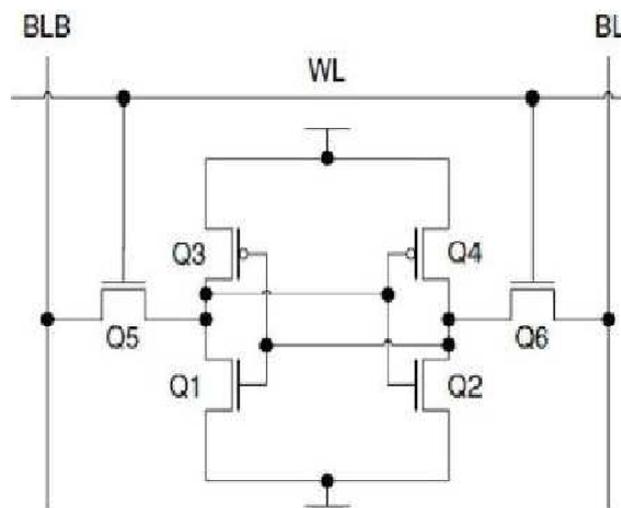


Figure 3: 6T CMOS SRAM Cell



### **8T AND 10T Sram Array Structure and Energy Estimation**

This section describes the analysis of different design parameters, in which the double  $V_{th}$  system plays a significant role in determining the impacts on the SRAM, the 8T and 10T SRAM structures and overall energy for the SRAM. We have chosen 10T SRAM for energy analysis.

### **Proposed Dual $V_{th}$ Scheme Effect ON SRAM**

For SRAM 6T, cell stabilization and occasional data inversion feature (i.e. change the status from "0" to "1" after reading a little cell or vice versa) or writing errors (i.e., writing to the data bit cell fails to overwrite the previously saved value). Some supporting devices such as single-end sensor cells are installed [4]-[8] and difference sensor cells [9], [10] to solve these problems. A new cell of SRAM was proposed. Single-end sensing cells generally aren't as robust as differential sensing cells, so additional compensation systems may have to maintain the reliability recommended in [7].

Moreover, thermal multiplexing (also known as interleaving bit) in which a single-end sensing cell share IO between multicell columns is not, but is not easy. By creating a conservative cell with two cross-coupling Schmitt triggers, cell stability and capacity were improved in a differential cell. This type of ST cell presents a minor problem. When a storage node with "0" data reads, there are still reading problems, which are a sign of a temporary voltage failure. This voltage problem enables the cell to reverse unexpectedly.

We have employed a dual  $V_{th}$  method with a 10T SRAM cell in our work. The behaviour of this cell is identical to that of the standard SRAM  $V_{th}$  10T cell except that there is a low  $V_{th}$  of the access transistors (PGL and PGR) and the downstream transistors (PDL2 and PDR2) are a high  $V_{th}$ . As mentioned above, the low  $V_{th}$  of the access transistor greatly improves the access speed of the transistor. This is helpful when quickly accessing data stored in SRAM cells. Furthermore, the high  $V_{th}$  transistor pull-downs reduce the leakage through these transistors. The cell performance is therefore increased as compared to the two SRAM  $V_{th}$  8T cells at the intersection between area and power.

### **8T SRAM Cell**

The figure below shows an 8T SRAM cell consisting of two pull-up pMOS transistors and two pull-down nMOS transistors. Single-port address lines and data are stored by SRAM. Therefore, SRAM can perform read or write operations simultaneously, so it is known as "1WR." Figure 5 shows an 8T-SRAM type 2WR (read/write) with an identical structure to the standard 8T single-port SRAM. Each address and data store line can individually perform writing and reading operations. Two sets of data storage addresses and data lines are data path storage cells in Figure 6. One can write here and the other can perform read operations (1W1R). These 8T-SRAMs have two types, 2WR can do 1W1R work, but 1W1R can not do 2WR cells work.

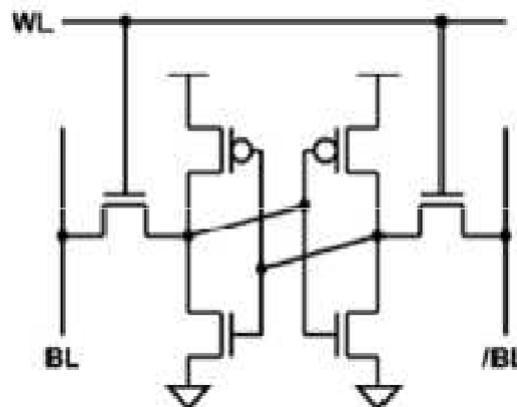


Figure 4: 6T Cell

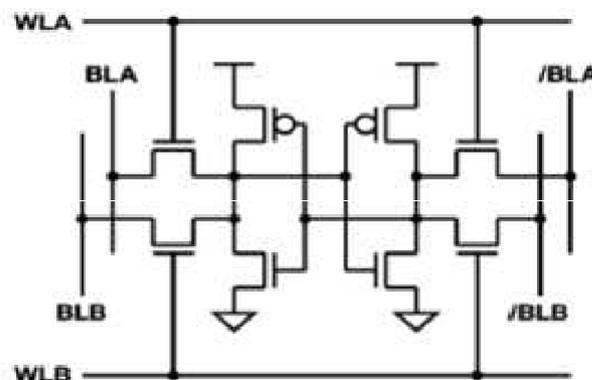


Figure 5: 8T Cell (1 Write)

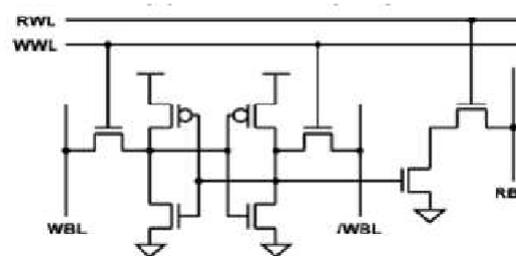


Figure 6: 8T Cell (1 Read 1 Write)

Therefore, a 2WR battery is more flexible than a 1W1R.1WR SRAM is used to store commands in many SOC projects. The memory cells can therefore be used to send generic records and registries requiring a write door and a read-gate. Three SRAM data paths handle SRAM 8T and SRAM 10T with a single reading gate and SRAM 10T with a single gate. This SEU occurs when charged particles damage nodes and change the state of a SRAM cell from 0 to 1.

The SRAM 10T is ideal for Double Door SRAMs with a single reading port. The SRAM 8T is the least transistor-efficient in its area, but has higher reading power and longer reading bitline, which results in longer cycle times. SRAM 10T works very quickly. The detection point is 50 mV with energy efficiency and most cells are disrupted by the power to use bit

lines greater than 50 mV. The SRAM 10T therefore always consumes the lowest measured power.

### Proposed 10T SRAM Cell

As the name suggests, the SRAM 10T cell (Figure 2) consists of 10 transistors. During the read process, this VGND signal is connected to ground, otherwise it is connected to VDD. The access transistor from the SRAM cell 10T is connected from the memory node (i.e. Q and Qb) to the medical node (pQ and pQb, the node between the two pull-up transistors). Therefore, if no read current flows through the storage node during a read operation, the storage node is isolated from the BL for read stability. VGND is connected to VDD for write operations, and one of the bit lines is grounded. When a high voltage is applied when the Q node stores '1' and the Qb node stores '0', e is accessed and discharged through the pull-up transistors PGL and PUL2, and the node Q becomes 0.

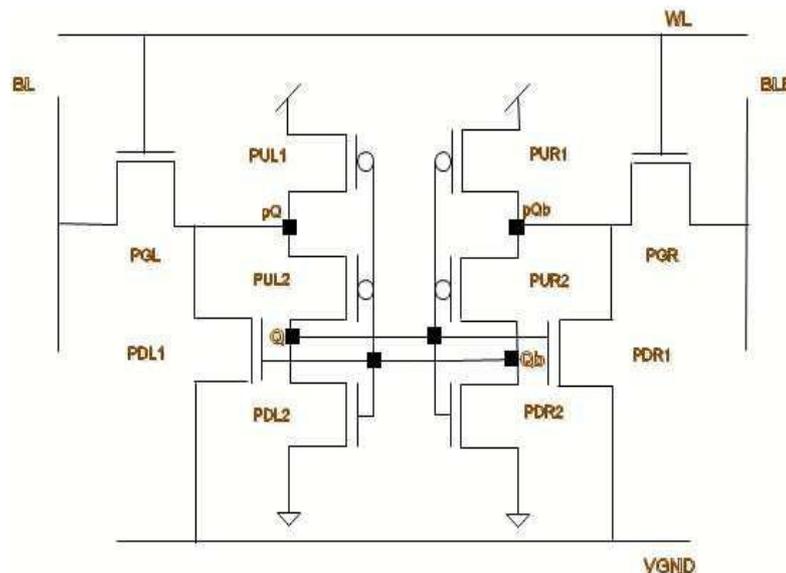


Figure 7: 10T SRAM Cell

Here we use standard Vth transistors, low Vth and high Vth pull-down transistors. Low Vth transistors reduce the gate voltage (Vg) required to activate the access transistors, greatly increasing the access speed of stored data. Additionally, high Vth pull-down transistors reduce circuit dispersion.

### Simulation Work

We have employed a dual Vth method with a 10T SRAM cell in our work. This is a standard SRAM Vth 10T cell, but it has a lower Vth for the access transistors used (PGL and PGR) and a higher Vth for the pull-down transistors (PDL2 and PDR2). As mentioned above, the low Vth of the access transistor greatly improves the access speed of the transistor. This is useful for fast access to data that is stored in SRAM cells. High Vth pull-down transistors also reduce leakage through these transistors. Therefore, compared to the area and energy efficiency of the SRAM Vth 8T dual cells the cell performance is increased.

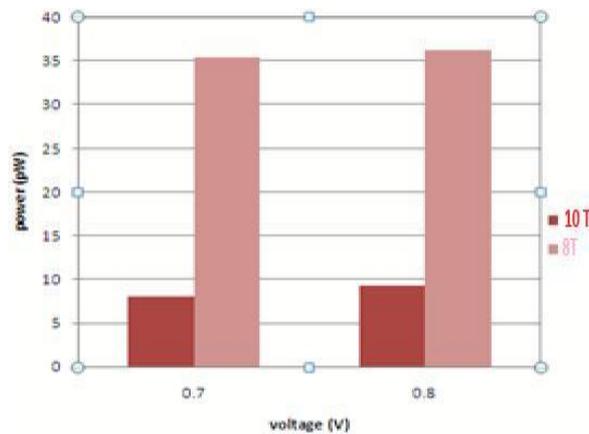


Figure 8: Comparison of Leakage Power of 8T and 10T

The static power consumption of a dual Vth 10T cell is shown in Figure 8, and a dual SRAM Vth 8T cell. As you can see, the leak power of the Vth 10T dual SRAM is 74 percent lower than the VDD dual Vth 8T cell = 0.8V and 0.7V respectively.

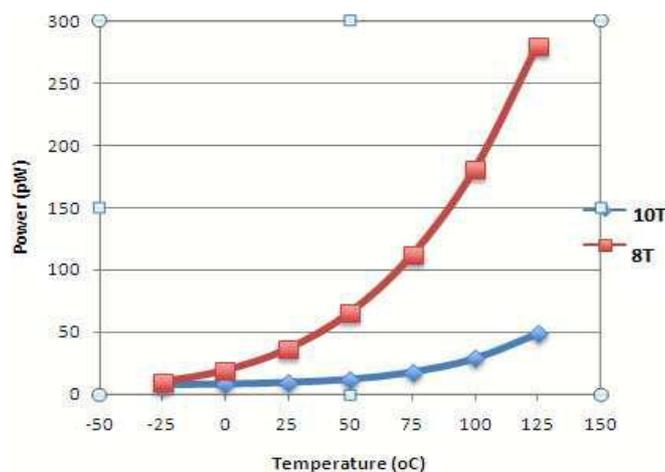
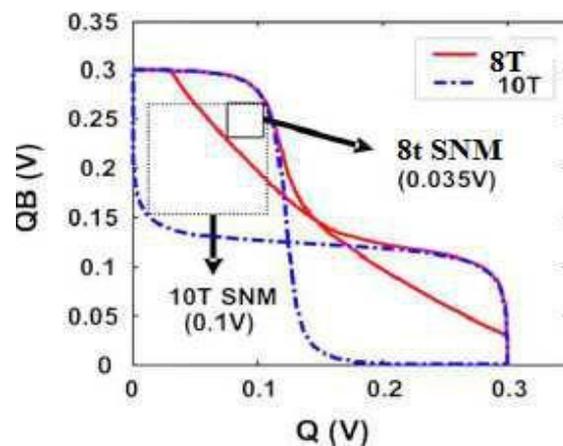


Figure 9: Effect of Temperature Variations on Conventional 8T and 10T SRAM Cell

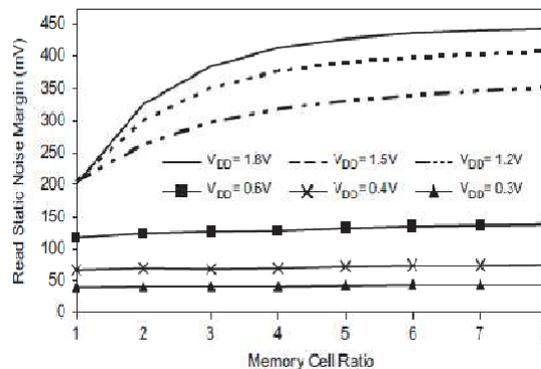
Figure 9 shows the temperature variation between 0.8V and -25 to 125°C for dual SRAM Vth 8T and 10T cells. In addition to reducing air loss, substantial SNM was observed, 0.42V at VDD = 0.8V and 0.37V at VDD = 0.7V.

## 2. RESULTS AND DISCUSSIONS

8T SRAM access time is the time after RWL reaches VDD/2. Access time from 10T SRAM is higher, i.e. from the moment the word line read (WLR) rises to VDD/2, the sensor amplifier output is loaded to VDD/2. It rises until it is released. The 10T SRAM access time will be the period from the moment the RWL reaches VDD/2 until the differential voltage of the RBL will be increased to 50mV, 100mV or 200mV.



(a)



(b)

Figure 10: Statistical Analysis of 10T (a) SNM Ratio of 8T and Proposed 10T and (b) Read SNM of Different Voltage in 10T

Afterwards, the energy efficiency of the SRAM array structure can be improved at 10T output, and the SNM ratio 10t can be simulated, as shown in Figures 10(a) and 10(b). We show therefore that a comparison of other transistors enables 10T, as shown in Table 1, which is used to increase energy efficiency.

Table 1: Comparison of Transistor

No of Transistor	Power	Area	Efficiency
4T	1.792mW	4.1mm	23.6%
6T	2.270mW	5.9mm	29.8%
8T	0.321mW	6.2mm	40%
10T	0.024μW	2.2mm	50%



### 3. CONCLUSIONS

In this paper, we analyze and simulate a P-P-N based 10T SRAM cell using a dual-V<sub>th</sub> approach (using deep submicron technology). Compared to 8T SRAM dual-bit cells at VDD = 0.8V and VDD = 0.7V, this reduces atmospheric partitioning by 74% and 77%, and improves energy efficiency by 50% and 20% without cell penalty.

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